



SOT1154-1

plastic dual bent surface mounted SIL power package; 27 leads

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	DBSMS27P
Package type industry code	DBSMS27P
Package style descriptive code	DBS (DIL-bent-SIL)
Package style suffix code	P (power)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	T (through-hole mount)
Issue date	13-2-2013

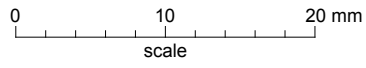
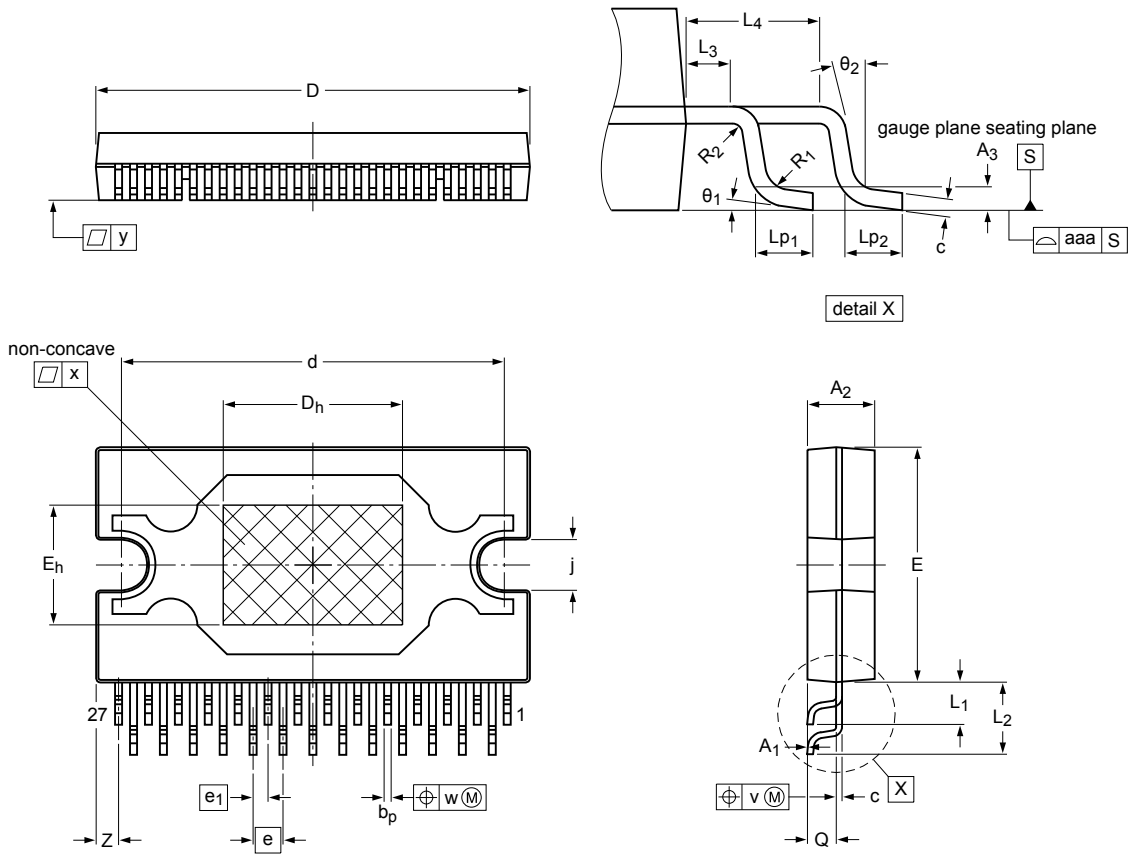
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	28.8	-	29	29.2	mm
E	package width	15.5	-	15.7	15.9	mm
A	seated height	4.35	-	4.5	4.65	mm
A ₂	package height	4.4	-	4.5	4.6	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	27	-	



2. Package outline

DBSMS27P: plastic dual bent surface mounted SIL power package; 27 leads SOT1154-1



R ₁	R ₂	aaa	v	w	x	y	Z ⁽¹⁾	θ ₁	θ ₂
0.85	0.35						1.8	9°	10°
0.60	0.25	0.1	0.6	0.25	0.03	0.1	1.5		
0.35	0.15						1.2	3°	4°

Dimensions

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	d	D _h	E ⁽¹⁾	e	e ₁	E _h	j	L ₁	L ₂	L ₃	L ₄	Lp ₁	Lp ₂	Q	
max	4.65	0.10	4.6		0.60	0.5	29.2	24.8		15.9					3.55	3.03	5.03	1.2	3.2	1.43	1.43	2.10
mm nom	4.50	0.00	4.5	0.5	0.50	0.4	29.0	24.6	12	15.7	2	1	8	3.40	2.83	4.83	1.0	3.0	1.25	1.25	1.95	
min	4.35	-0.08	4.4		0.45	0.3	28.8	24.4		15.5					3.25	2.63	4.63	0.8	2.8	1.07	1.07	1.80

Note
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1154-1	---	---	---		-12-12-19- 13-02-13

Fig. 1. Package outline DBSMS27P (SOT1154-1)

3. Legal information

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